

## Physical Interface & Carriers Japan TC Chapter

Japan Standards Winter 2018 Meetings in conjunction with SEMICON Japan 2018  
Wednesday, December 12, 2018  
Conference Tower, Tokyo big Sight, Tokyo, Japan  
14:00 – 17:00

### AGENDA

#### 1.0 Welcome / Call to Order

- 1.1 Introductions
- 1.2 Meeting Reminders (*Membership Requirement, Antitrust and Intellectual Property Reminders, Effective Meeting Guidelines*)
- 1.3 Agenda Review

#### 2.0 Review of Previous Meeting Minutes

#### 3.0 Liaison Report

- 3.1 Europe
- 3.2 North America

#### 4.0 Staff Report

#### 5.0 Ballot Review

- 5.1 #6444: Line Item Revision to SEMI E152-0214: “MECHANICAL SPECIFICATION OF EUV POD FOR 150 mm EUVL RETICLES” with non-conforming title change to “SPECIFICATION FOR MECHANICAL FEATURES OF EUV POD FOR 150 mm EUVL RETICLES”
- 5.2 #6445: Line Item Revision to SEMI E154-0814E: “MECHANICAL INTERFACE SPECIFICATION FOR 450 mm LOAD PORT” with non-conforming title change to “SPECIFICATION FOR MECHANICAL FEATURES OF 450 mm LOAD PORT”
- 5.3 #6446: Line Item Revision to SEMI E158-0314E: “MECHANICAL SPECIFICATION FOR FAB WAFER CARRIER USED TO TRANSPORT AND STORE 450 mm WAFERS (450 FOUP) AND KINEMATIC COUPLING” with non-conforming title change to “SPECIFICATION FOR MECHANICAL FEATURES OF FAB WAFER CARRIER USED TO TRANSPORT AND STORE 450 mm WAFERS (450 FOUP) AND KINEMATIC COUPLING”
- 5.4 #6447: Line Item Revision to SEMI E159-0314E: “MECHANICAL SPECIFICATION FOR MULTI APPLICATION CARRIER (MAC) USED TO TRANSPORT AND SHIP 450 mm WAFERS” with non-conforming title change to “SPECIFICATION FOR MECHANICAL FEATURES OF MULTI APPLICATION CARRIER (MAC) USED TO TRANSPORT AND SHIP 450 mm WAFERS”

#### 6.0 Subcommittee & Task Force Reports

- 6.1 300 mm Tape Frame PI&C TF
- 6.2 Fan-Out Panel Level Packaging (FO-PLP) Panel FOUP TF
- 6.3 Global PIC Standards Maintenance TF
- 6.4 Japan Electron Microscopy Workflow liaison TF
- 6.5 [Liaison: Silicon Wafer Japan TC Chapter] JA Shipping Box TF
- 6.6 [Liaison: Silicon Wafer Japan TC Chapter / PI&C TC NA TC Chapter] International 450mm Shipping Box
- 6.7 [Liaison: 3D Packaging & Integration NA TC Chapter] Fan-Out Panel Level Packaging (FO-PLP) Panel TF



**7.0 Old Business**

**8.0 New Business**

8.1 Proposal for New SNARFs by Fan-Out Panel Level Packaging (FO-PLP) Panel FOUP Task Force

8.2 Proposal for additional task force leaders of 300 mm Tape Frame PI&C Task Force

**9.0 Action Item Review**

9.1 Open Action Items

9.2 New Action Items

**10.0 Next Meeting and Adjournment**